

CHIP ELEMENT HOLDER AND METHOD OF HANDLING CHIP ELEMENTS

ABSTRACT OF THE DISCLOSURE

Exact transfer of electronic element main bodies, held by virtue of an adhesive property provided by an adhesive surface, is provided from a first holder to a second holder. A plurality of through holes are formed in the first holder, so that a pressing force provided by a pusher member can be applied through the through holes to the electronic element main bodies bonded on an adhesive surface of the first holder. Meanwhile, the first holder is separated from the electronic element main bodies which are at the same time bonded on to an adhesive surface of the second holder.

Figure. 4



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